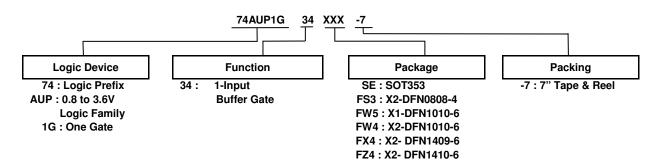


# **Ordering Information**



Device	Package	Package	Package	7" Tape :	and Reel
Device	Code	(Notes 4 & 5)	Size	Quantity	Part Number Suffix
74AUP1G34SE-7	SE	SOT353	2.0mm x 2.0mm x 1.1mm 0.65 mm lead pitch	3,000/Tape & Reel	-7
74AUP1G34FS3-7	FS3	X2-DFN0808-4	0.8mm x 0.8mm x 0.35mm 0.5 mm pad pitch (diamond)	5,000/Tape & Reel	-7
74AUP1G34FW5-7	FW5	X1-DFN1010-6	1.0mm x 1.0mm x 0.5mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G34FW4-7	FW4	X2-DFN1010-6	1.0mm x 1.0mm x 0.4mm 0.35 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G34FX4-7	FX4	X2-DFN1409-6 Chip Scale Alternative	1.4mm x 0.9mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7
74AUP1G34FZ4-7	FZ4	X2-DFN1410-6	1.4mm x 1.0mm x 0.4mm 0.5 mm pad pitch	5,000/Tape & Reel	-7

Notes: 4. Pad layout as shown on Diodes Inc. suggested pad layout document AP02001, which can be found on our website at

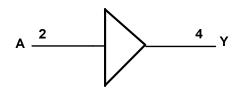
http://www.diodes.com/datasheets/ap02001.pdf.

5. The taping orientation is located on our website at http://www.diodes.com/datasheets/ap02007.pdf.

## **Pin Descriptions**

Pin Name	Function			
NC	No Connection			
A	Data Input			
GND	Ground			
Y	Data Output			
V <sub>CC</sub>	Supply Voltage			

# Logic Diagram



## **Function Table**

Inputs	Output
Α	Y
Н	Н
L	L



#### Absolute Maximum Ratings (Notes 6 & 7) (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Symbol	Parameter	Rating	Unit
ESD HBM	Human Body Model ESD Protection	2	kV
ESD CDM	Charged Device Model ESD Protection	1	kV
V <sub>CC</sub>	Supply Voltage Range	-0.5 to +4.6	V
VI	Input Voltage Range	-0.5 to +4.6	V
Vo	Voltage Applied to Output in High or Low State	-0.5 to V <sub>CC</sub> +0.5	V
l <sub>IK</sub>	Input Clamp Current (VI < 0)	50	mA
I <sub>OK</sub>	Output Clamp Current (V <sub>O</sub> < 0)	50	mA
lo	Continuous Output Current (V <sub>O</sub> = 0 to V <sub>CC</sub> )	±20	mA
lcc	Continuous Current Through V <sub>CC</sub>	50	mA
I <sub>GND</sub>	Continuous Current Through GND	-50	mA
TJ	Operating Junction Temperature	-40 to +150	°C
T <sub>STG</sub>	Storage Temperature	-65 to +150	°C

Notes: 6. Stresses beyond the absolute maximum may result in immediate failure or reduced reliability. These are stress values and device operation should be within recommend values.

7. Forcing the maximum allowed voltage could cause a condition exceeding the maximum current or conversely forcing the maximum current could cause a condition exceeding the maximum voltage. The ratings of both current and voltage must be maintained within the controlled range.

Symbol	P	arameter	Min	Max	Unit
V <sub>CC</sub>	Operating Voltage		0.8	3.6	v
VI	Input Voltage		0	3.6	V
Vo	Output Voltage		0	V <sub>CC</sub>	V
		$V_{CC} = 0.8V$	—	-20	μA
		V <sub>CC</sub> = 1.1V	-	-1.1	
		V <sub>CC</sub> = 1.4V	—	-1.7	
I <sub>OH</sub>	High-Level Output current	V <sub>CC</sub> = 1.65V	—	-1.9	mA
		V <sub>CC</sub> = 2.3V	—	-3.1	
		$V_{CC} = 3.0V$	—	-4	
		V <sub>CC</sub> = 0.8V	-	20	μΑ
		V <sub>CC</sub> = 1.1V	-	1.1	
		$V_{CC} = 1.4V$	—	1.7	
IOL	Low-Level Output Current	V <sub>CC</sub> = 1.65V	—	1.9	mA
		V <sub>CC</sub> = 2.3V	—	3.1	
		$V_{CC} = 3.0V$	—	4	
Δt/ΔV	Input Transition Rise or Fall Rate	V <sub>CC</sub> = 0.8V to 3.6V	_	200	ns/V
T <sub>A</sub>	Operating Free-Air Temperature	1	-40	+125	°C

#### Recommended Operating Conditions (Note 8) (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Note: 8. Unused inputs should be held at  $V_{\text{CC}}$  or Ground.



## Electrical Characteristics (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Symbol	Parameter	Test Conditions	Vee	T <sub>A</sub> = -	+25°C	T <sub>A</sub> = -40℃	C to +85 ℃	Unit
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Min	Max	Unit
		—	0.8V to 1.65V	0.80 x V <sub>CC</sub>	—	0.80 x V <sub>CC</sub>	—	
V <sub>IH</sub>	High-Level Input	—	1.65V to 1.95V	0.65 x V <sub>CC</sub>	—	0.65 x V <sub>CC</sub>	—	V
VН	Voltage	_	2.3V to 2.7V	1.6	—	1.6	—	v
			3.0V to 3.6V	2.0		2.0	_	
		_	0.8V to 1.65V		$0.30 \times V_{CC}$	—	$0.30 \times V_{CC}$	
V <sub>IL</sub>	Low-Level Input	_	1.65V to 1.95V	—	$0.35 \times V_{CC}$	—	$0.35 \times V_{CC}$	V
VIL	Voltage	—	2.3V to 2.7V	—	0.7	—	0.7	
			3.0V to 3.6V		0.9	_	0.9	
		I <sub>OH</sub> = -20μA	0.8V to 3.6V	V <sub>CC</sub> - 0.1	—	V <sub>CC</sub> – 0.1	—	
		I <sub>OH</sub> = -1.1mA	1.1V	$0.75 \times V_{CC}$	—	$0.7 \times V_{CC}$	—	
		I <sub>OH</sub> = -1.7mA	1.4V	1.11	—	1.03	_	
V	High-Level	I <sub>OH</sub> = -1.9mA	1.65V	1.32	—	1.3	—	V
∨он	VOH Output Voltage	I <sub>OH</sub> = -2.3mA	0.01/	2.05	—	1.97	—	V
		I <sub>OH</sub> = -3.1mA	2.3V	1.9	—	1.85	—	
		I <sub>OH</sub> = -2.7mA	0)/	2.72	—	2.67	_	
		I <sub>OH</sub> = -4mA	3V	2.6	—	2.55	_	
		l <sub>OL</sub> = 20μA	0.8V to 3.6V	—	0.1		0.1	
		I <sub>OL</sub> = 1.1mA	1.1V	—	0.3 x V <sub>CC</sub>	—	0.3 x V <sub>CC</sub>	
		I <sub>OL</sub> = 1.7mA	1.4V		0.31		0.37	
	Low-Level	I <sub>OL</sub> = 1.9mA	1.65V	—	0.31	—	0.35	
V <sub>OL</sub>	Output Voltage	I <sub>OL</sub> = 2.3mA			0.31		0.33	V
		I <sub>OL</sub> = 3.1mA	2.3V		0.44	—	0.45	
		I <sub>OL</sub> = 2.7mA		—	0.31	—	0.33	
		I <sub>OL</sub> = 4mA	3V	_	0.44	_	0.45	
lı	Input Current	A or B Input V <sub>I</sub> = GND to 3.6V	0 to 3.6V		±0.1		±0.5	μA
IOFF	Power Down Leakage Current	$V_{I}$ or $V_{O} = 0V$ to 3.6V	0	_	0.2	_	0.6	μA
Δloff	Delta Power Down Leakage Current	$V_{\rm I}$ or $V_{\rm O}$ = 0V to 3.6V	0 to 0.2V		0.2		0.6	μA
Icc	Supply Current	$V_I = GND \text{ or } V_{CC}, I_O = 0$	0.8V to 3.6V	—	0.5	—	0.9	μA
Δlcc	Additional Supply Current	Input at V <sub>CC</sub> -0.6	3.3V	—	40	—	50	μA



#### Electrical Characteristics (continued) (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

Cumhal	Deremeter	Test Conditions	N	T <sub>A</sub> = -40 °C	C to +125℃	Unit
Symbol	Parameter	Test Conditions	Vcc	Min	Max	Unit
		—	0.8V to 1.65V	$0.80 \times V_{CC}$	—	
V <sub>IH</sub>	High-Level Input	_	1.65V to 1.95V	0.70 x V <sub>CC</sub>	—	v
VН	Voltage		2.3V to 2.7V	1.6	_	v
		_	3.0V to 3.6V	2.0	_	
		_	0.8V to 1.65V	—	$0.25 \times V_{CC}$	
V <sub>IL</sub>	Low-Level Input	_	1.65V to 1.95V	_	$0.30 \times V_{CC}$	V
۷IL	Voltage	_	2.3V to 2.7V	_	0.7	, i i i i i i i i i i i i i i i i i i i
		_	3.0V to 3.6V	—	0.9	
		I <sub>OH</sub> = -20μA	0.8V to 3.6V	V <sub>CC</sub> – 0.11	—	
		I <sub>OH</sub> = -1.1mA	1.1V	$0.6 \times V_{CC}$	—	
	High-Level	I <sub>OH</sub> = -1.7mA	1.4V	0.93	—	
Maria		I <sub>OH</sub> = -1.9mA	1.65V	1.17	_	v
∨он		I <sub>OH</sub> = -2.3mA	2.3V	1.77	—	v
		I <sub>OH</sub> = -3.1mA	2.3V	1.67	—	
		I <sub>OH</sub> = -2.7mA	- 3V	2.40	—	
		I <sub>OH</sub> = -4mA	3V	2.30		
		I <sub>OL</sub> = 20μA	0.8V to 3.6V	_	0.11	
		I <sub>OL</sub> = 1.1mA	1.1V	_	0.33 x V <sub>CC</sub>	
		I <sub>OL</sub> = 1.7mA	1.4V	_	0.41	
	Low-Level	I <sub>OL</sub> = 1.9mA	1.65V	_	0.39	
V <sub>OL</sub>	Output Voltage	I <sub>OL</sub> = 2.3mA	0.01/	_	0.36	V
		I <sub>OL</sub> = 3.1mA	2.3V	_	0.50	
		I <sub>OL</sub> = 2.7mA	<u>a) (</u>	_	0.36	
		I <sub>OL</sub> = 4mA	- 3V	_	0.50	
II.	Input Current	A or B Input VI = GND to 3.6V	0 to 3.6V	_	±0.75	μΑ
IOFF	Power Down Leakage Current	$V_{\rm I}$ or $V_{\rm O} = 0$ to 3.6V	0	_	±3.5	μΑ
ΔI <sub>OFF</sub>	Delta Power Down Leakage Current	$V_{\rm I}$ or $V_{\rm O}$ = 0 to 3.6V	0 to 0.2V	_	±2.5	μA
I <sub>CC</sub>	Supply Current	$V_I = GND \text{ or } V_{CC}, I_O = 0$	0.8V to 3.6V	—	3.0	μA
ΔI <sub>CC</sub>	Additional Supply Current	Input at $V_{CC}$ -0.6V Other Inputs at $V_{CC}$ or GND	3.3V	_	75	μΑ



# **Switching Characteristics**

Parameter	r From To Input Output	То	V	٦	Γ <sub>A</sub> = +25℃	2	T <sub>A</sub> = -40 ℃	T <sub>A</sub> = -40 ℃ to +85 ℃		to +125℃	Unit
Farameter		Output	V <sub>CC</sub>	Min	Тур	Max	Min	Max	Min	Max	Unit
		0.8V	_	15.0	—	—	_	_	—		
		ВҮ	1.2V ± 0.1V	2.6	4.7	9.2	2.0	10.0	2.0	11.0	- ns
	A or D		1.5V ± 0.1V	2.1	3.4	5.7	1.6	6.5	1.6	7.2	
t <sub>pd</sub> A or B	AUD		1.8V ± 0.15V	1.8	2.9	4.5	1.4	5.2	1.4	5.8	
			2.5V ± 0.2V	1.5	2.3	3.5	1.2	4.2	1.2	4.6	
			3.3V ± 0.3V	1.0	2.1	3.2	1.0	3.8	1.0	4.2	

#### CL=10pF, See Figure 1

Parameter	From Input	To Output	Vcc	٦	T <sub>A</sub> = +25 ℃			T <sub>A</sub> = -40 ℃ to +85 ℃		T <sub>A</sub> = -40 ℃ to +125 ℃	
Farameter			V CC	Min	Тур	Max	Min	Max	Min	Max	Unit
			0.8V	_	18.4	_	_	—	_	—	
		Y	1.2V ± 0.1V	3.2	5.6	10.9	2.3	11.8	2.3	13.1	
	A or B		1.5V ± 0.1V	2.6	4.1	6.7	1.9	7.7	1.9	8.5	
t <sub>pd</sub>	AUD		1.8V ± 0.15V	2.3	3.4	5.3	1.7	6.2	1.7	6.9	ns
			2.5V ± 0.2V	2.0	2.9	4.2	1.5	5.0	1.5	5.5	
			3.3V ± 0.3V	1.4	2.6	3.8	1.4	4.6	1.4	5.1	

#### CL=15pF, See Figure 1

Parameter	From Input	To Output	V <sub>cc</sub>	٦	T <sub>A</sub> = +25 ℃			T <sub>A</sub> = -40 ℃ to +85 ℃		T <sub>A</sub> = -40 ℃ to +125 ℃	
			V CC	Min	Тур	Max	Min	Max	Min	Max	Unit
			0.8V	_	21.9	_	_	—	_	—	
		r B Y	1.2V ± 0.1V	3.6	6.4	12.6	2.6	13.8	2.6	15.2	ns
+	A or B		1.5V ± 0.1V	3.0	4.6	7.6	2.2	8.9	2.2	9.8	
t <sub>pd</sub>	AUD		1.8V ± 0.15V	2.6	3.9	6.0	2.0	7.2	2.0	7.9	
			2.5V ± 0.2V	2.3	3.3	4.8	1.8	5.7	1.8	6.3	
			$3.3V \pm 0.3V$	1.6	3.1	4.2	1.6	5.0	1.6	5.5	

#### CL=30pF, See Figure 1

Parameter	From Input	To Output	Vaa	T <sub>A</sub> = +25 ℃			T <sub>A</sub> = -40 ℃ to +85 ℃		T <sub>A</sub> = -40 ℃ to +125 ℃		Unit
			Vcc	Min	Тур	Min	Min	Max	Min	Max	Onit
			0.8V	_	32.1	_	—	_	_	_	
		Y	1.2V ± 0.1V	4.8	8.9	16.3	3.6	18.9	3.6	20.8	
	A or B		1.5V ± 0.1V	4	6.2	10.3	3.4	12.2	3.4	13.4	
t <sub>pd</sub>	AUD		1.8V ± 0.15V	3.6	5.2	8.1	3.2	9.8	3.2	10.8	ns
			2.5V ± 0.2V	3	4.4	6.4	2.7	7.7	2.7	8.5	
			3.3V ± 0.3V	1.9	4.2	5.6	1.9	6.5	1.9	7.2	



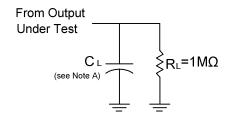
# Operating and Package Characteristics (@T<sub>A</sub> = +25 °C, unless otherwise specified.)

	Parameter	Test Conditio		Vcc	Тур	Unit
				0.8V	6.7	
				1.2V ± 0.1V	6.6	
0	Power Dissipation	f = 1MH	lz	1.5V ± 0.1V	6.5	~ <b>F</b>
CPD	Capacitance	No Loa	d	1.8V ± 0.15V	6.5	рF
				2.5V ± 0.2V	6.4	
				3.3V ± 0.3V	6.3	
CI	Input Capacitance	VI = VCC or	GND	0V or 3.3V	1.5	pF
		SOT353		-	371	
		X2-DFN0808-4			430	
0	Thermal Resistance	X1-DFN1010-6		_	435	~~~~
$\theta_{JA}$	Junction-to-Ambient	X2-DFN1010-6	(Note 9)		445	°C/W
		X2-DFN1409-6			470	
		X2-DFN1410-6			460	
		SOT353			143	
		X2-DFN0808-4			240	
•	Thermal Resistance	X1-DFN1010-6		_	250	~~~~~
$\theta_{\text{JC}}$	Junction-to-Case	X2-DFN1010-6	(Note 9)	_	250	°C/W
		X2-DFN1409-6	1	_	275	
		X2-DFN1410-6		_	265	

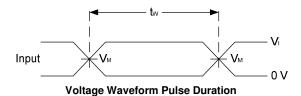
Note: 9. Test condition for each of the six package types: Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.



## **Parameter Measurement Information**



Vcc	Inputs		X	0
	VI	t <sub>r</sub> /t <sub>f</sub>	VM	CL
0.8V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
1.2V±0.1V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
1.5V±0.1V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
1.8V ±0.15V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
2.5V±0.2V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF
3.3V±0.3V	V <sub>CC</sub>	≤3ns	V <sub>CC</sub> /2	5, 10, 15, 30pF



V Input ЧM ÝΜ 0 V ₽LH teнu Vон Output Vм Vol t₽HL Vон Output – Vol

Voltage Waveform Propagation Delay Times Inverting and Non Inverting Outputs

#### Figure 1 Load Circuit and Voltage Waveforms

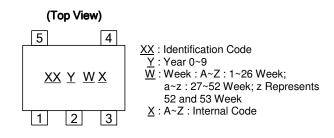
Notes: A. Includes test lead and test apparatus capacitance. B. All pulses are supplied at pulse repetition rate  $\leq$  10MHz.

- C. Inputs are measured separately one transition per measurement.
- D. tPLH and tPHL are the same as tPD.



#### **Marking Information**

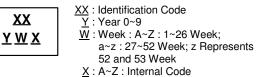
(1) SOT353



Part Number	Package	Identification Code
74AUP1G34SE-7	SOT353	XV

#### (2) X2-DFN0808-4, X1-DFN1010-6, X2-DFN1010-6, X2-DFN1409-6 and X2-DFN1410-6

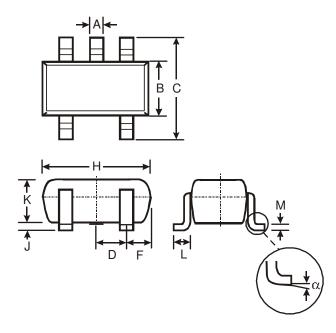




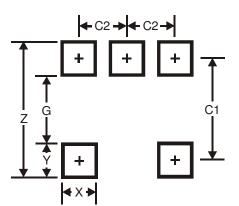
Part Number	Package	Identification Code
74AUP1G34FS3-7	X2-DFN0808-4	WK
74AUP1G34FW5-7	X1-DFN1010-6	QV
74AUP1G34FW4-7	X2-DFN1010-6	XV
74AUP1G34FX4-7	X2-DFN1409-6	HM
74AUP1G34FZ4-7	X2-DFN1410-6	XV



## SOT353 Package Outline Dimensions and Suggested Pad Layout



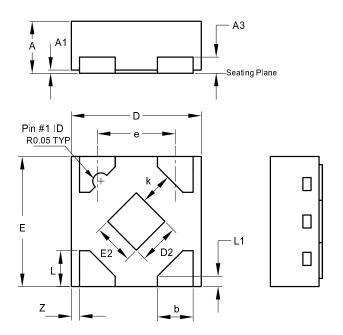
	SOT353				
Dim	Min	Max	Тур		
Α	0.10	0.30	0.25		
В	1.15	1.35	1.30		
С	2.00	2.20	2.10		
D		0.65 Typ	)		
F	0.40	0.45	0.425		
н	1.80	2.20	2.15		
J	0	0.10	0.05		
К	0.90	1.00	1.00		
L	0.25	0.40	0.30		
М	0.10	0.22	0.11		
α	0°	8°	-		
A	All Dimensions in mm				



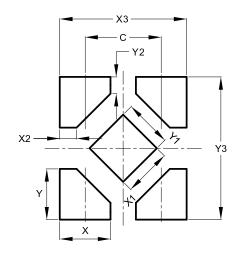
Dimensions	Value (in mm)
Z	2.5
G	1.3
Х	0.42
Y	0.6
C1	1.9
C2	0.65



#### X2-DFN0808-4 Package Outline Dimensions and Suggested Pad Layout



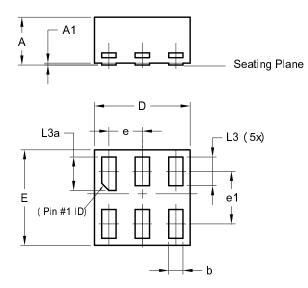
	X2-DFN0808-4					
Dim	Min	Max	Тур			
Α	0.25	0.35	0.30			
A1	0	0.04	0.02			
A3	-	-	0.13			
b	0.17	0.27	0.22			
D	0.75	0.85	0.80			
D2	0.15	0.35	0.25			
E	0.75	0.85	0.80			
E2	0.15	0.35	0.25			
е	-	-	0.48			
K	0.20	-	-			
L	0.17	0.27	0.22			
L1	0.02	0.12	0.07			
Z	-	-	0.05			
All Dimensions in mm						
<u> </u>						



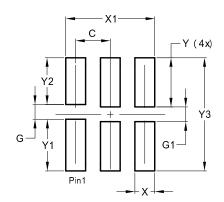
Dimensions	Value
С	0.480
Х	0.320
X1	0.300
X2	0.106
X3	0.800
Y	0.320
Y1	0.300
Y2	0.106
Y3	0.900



# X1-DFN1010-6 (Type B) Package Outline Dimensions and Suggested Pad Layout



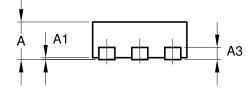
X1-DFN1010-6				
	(Ту	vpe B)		
Dim	Min	Max	Тур	
Α	-	0.50	0.39	
A1	-	0.04	-	
b	0.12	0.20	0.15	
D	0.95	1.050	1.00	
Е	0.95	1.050	1.00	
е		0.35 BSC		
e1		0.55 B	SC	
L3	0.27	0.30	0.30	
L3a	0.32	0.40	0.35	
All Dimensions in mm				

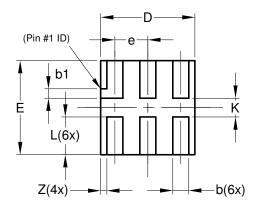


Dimensions	Value (in mm)
С	0.350
G	0.150
G1	0.150
Х	0.200
X1	0.900
Y	0.500
Y1	0.525
Y2	0.475
Y3	1.150

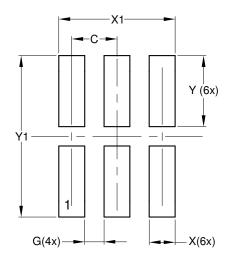


#### X2-DFN1010-6 Package Outline Dimensions and Suggested Pad Layout





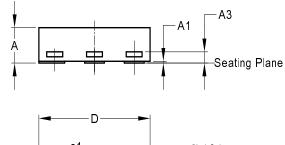
X2-DFN1010-6				
Dim	Min	Max	Тур	
Α	-	0.40	0.39	
A1	0.00	0.05	0.02	
A3	-	-	0.13	
b	0.14	0.20	0.17	
b1	0.05	0.15	0.10	
D	0.95	1.05	1.00	
E	0.95	1.05	1.00	
е	_	-	0.35	
L	0.35	0.45	0.40	
ĸ	0.15	_	_	
Z	_	_	0.065	
All Dimensions in mm				



Dimensions	Value (in mm)
С	0.350
G	0.150
X	0.200
X1	0.900
Y	0.550
Y1	1.250

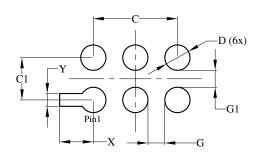


#### X2-DFN1409-6 Package Outline Dimensions and Suggested Pad Layout



	-	—D—			
(Pi <u>n #</u> 1 ID)	-	e1 ►		—Ø (6>	()
	$\overline{\bigcirc}$	$\bigcirc$	Ø	e2	
É –	$\square$	-+	$\frac{1}{2}$		
<u> </u>		$\rightarrow$	$\square$		
->		Z1 (4x)	Z2	( 4x)	

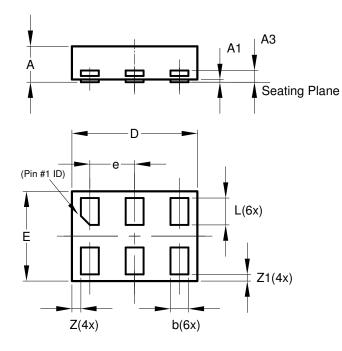
X2-DFN1409-6					
Dim	Min	Max	Тур		
Α	-	0.40	0.39		
A1	0	0.05	0.02		
A3	-	-	0.13		
Ø	0.20	0.30	0.25		
D	1.35	1.45	1.40		
Е	0.85	0.95	0.90		
e1	-	-	0.50		
e2	-	-	0.50		
Z1	-	-	0.075		
Z2	-	-	0.075		
All Dimensions in mm					



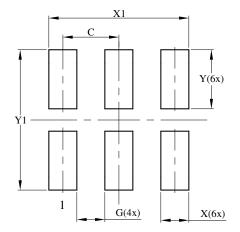
Dimensions	Value (in mm)	
С	1.000	
C1	0.500	
D	0.300	
G	0.200	
G1	0.200	
Х	0.400	
Y	0.150	



#### X2-DFN1410-6 Package Outline Dimensions and Suggested Pad Layout



X2-DFN1410-6				
Dim	Min	Max	Тур	
Α		0.40	0.39	
A1	0.00	0.05	0.02	
A3			0.13	
b	0.15	0.25	0.20	
D	1.35	1.45	1.40	
E	0.95	1.05	1.00	
е		_	0.50	
L	0.25	0.35	0.30	
Z	_		0.10	
Z1	0.045	0.105	0.075	
All Dimensions in mm				



Dimensions	Value (in mm)	
С	0.500	
G	0.250	
Х	0.250	
X1	1.250	
Y	0.525	
Y1	1.250	



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